

SOT-23 Formed SMD Package

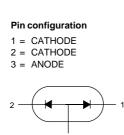
BAW56

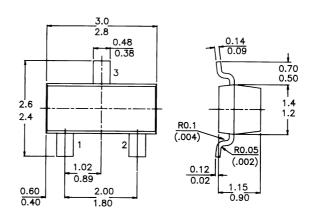
SILICON PLANAR EPITAXIAL HIGH-SPEED DIODES

Silicon planar high-speed switching Common Anode

Marking BAW56 = A1

PACKAGE OUTLINE DETAILS ALL DIMENSIONS IN mm





ABSOLUTE MAXIMUM RATINGS

Continuous reverse voltage	V_R	max.	75 V
Repetitive peak reverse voltage	V_{RRM}	max.	85 V
Repetitive peak forward current	I_{FRM}	max.	450 mA
Junction temperature	T_{j}	max.	150 ℃
Forward voltage at $I_F = 50 \text{ mA}$	${V}_F$	<	1,0 V
Reverse recovery time when switched from			
$I_F=10~mA$ to $I_R=10~mA$; $R_L=100~\Omega$;			
measured at $I_R = 1 \text{ mA}$	t_{rr}	<	4 ns
Recovery charge when switched from			
I_F = 10 mA to V_R = 5 V; R_L = 100 Ω	Q_S	<	45 pC

RATINGS (per diode) (at $T_A = 25$ °C unless otherwise specified)

Limiting values

Continuous reverse voltage V_R max. 75 V Repetitive peak reverse voltage V_{RRM} max. 85 V

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Forward current (d.c.)	I_F	max.	215 mA
Repetitive peak forward current	I_{FRM}	max.	450 mA
Non-repetitive peaK forward current			
(per crystal)			
$t = 1 \mu s$	I_{FSM}	max.	4 A
t = 1 ms	I_{FSM}	max.	1 A
t = 1 s	I_{FSM}	max.	0,5 A
Storage temperature range	T_{stg}	-55 to	o +150 ℃
Junction temperature	T_j	max.	150 ℃
THERMAL RESISTANCE			
From junction to ambient	R _{thj-a}	=	<i>500</i> KW
CHARACTERISTICS (per diode) (at $T_A = 25^{\circ}C$ unless other	herwise specifi	ied)	
$T_i = 25$ °C unless otherwise specified	•		
Forward voltage			
$I_F = 1 \text{ mA}$	V_F	<	715 mV
$I_F = 10 \text{ mA}$	V_F	<	855 mV
$I_F = 50 \text{ mA}$	V_F	<	1000 mV
$I_F = 150 \text{ mA}$	V_F	<	1250 mV
Reverse current			
$V_R = 25V; T_j = 150 {}^{\circ}C$	I_R	<	$30 \mu A$
$V_R = 75 V$	I_R	<	$1.0 \mu A$
$V_R = 75V; T_j = 150 {}^{\circ}C$	I_R	<	$50 \mu A$
Diode capacitance			
$V_R = 0$; $f = 1 MHz$	C_d	<	2,0 pF
Forward recovery voltage when switched to			
$I_F = 10mA$; $t_\Gamma = 20ns$	V_{fr}	<	1,75 V